

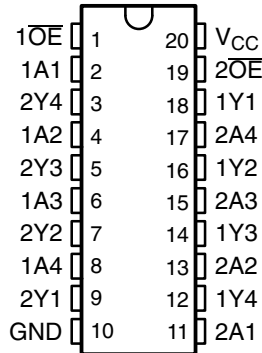
SN74LVT244B

3.3-V ABT OCTAL BUFFER/DRIVER WITH 3-STATE OUTPUTS

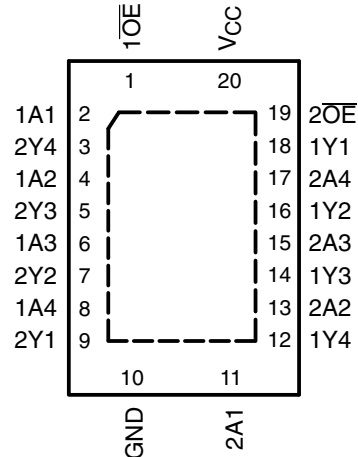
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- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Supports Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- I_{off} and Power-Up 3-State Support Hot Insertion
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DB, DW, NS, OR PW PACKAGE
(TOP VIEW)



RGY PACKAGE
(TOP VIEW)



description/ordering information

This octal buffer and line driver is designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The SN74LVT244B is organized as two 4-bit line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

ORDERING INFORMATION

| T_A | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|---------------|-----------------------|---------------|-----------------------|------------------|
| –40°C to 85°C | QFN – RGY | Tape and reel | SN74LVT244BRGYR | LX244B |
| | SOIC – DW | Tube | SN74LVT244BDW | LVT244B |
| | | Tape and reel | SN74LVT244BDWR | |
| | SOP – NS | Tape and reel | SN74LVT244BNSR | LVT244B |
| | SSOP – DB | Tape and reel | SN74LVT244BDBR | LX244B |
| | TSSOP – PW | Tube | SN74LVT244BPW | LX244B |
| | | Tape and reel | SN74LVT244BPWR | |
| | VFBGA – GQN | Tape and reel | SN74LVT244BGQNR | LX244B |
| | VFBGA – ZQN (Pb-free) | | SN74LVT244BZQNR | |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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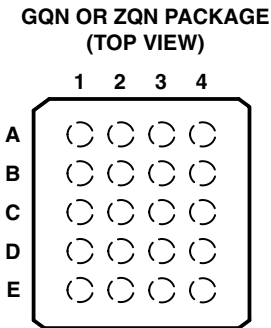
SN74LVT244B
3.3-V ABT OCTAL BUFFER/DRIVER
WITH 3-STATE OUTPUTS

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description/ordering information (continued)

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.



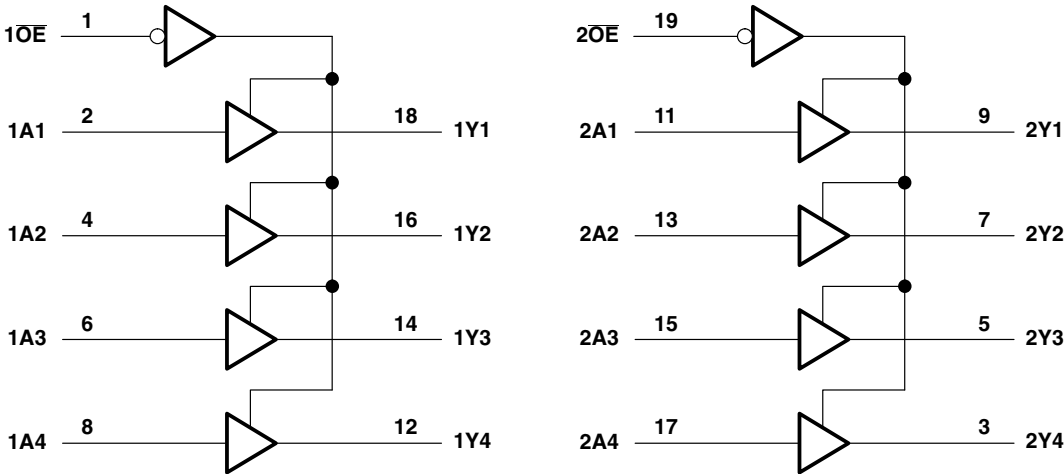
terminal assignments

| | 1 | 2 | 3 | 4 |
|---|-----|------------------|----------|------------------|
| A | 1A1 | $1\overline{OE}$ | V_{CC} | $2\overline{OE}$ |
| B | 1A2 | 2A4 | 2Y4 | 1Y1 |
| C | 1A3 | 2Y3 | 2A3 | 1Y2 |
| D | 1A4 | 2A2 | 2Y2 | 1Y3 |
| E | GND | 2Y1 | 2A1 | 1Y4 |

FUNCTION TABLE
(each 4-bit buffer)

| INPUTS | | OUTPUT Y |
|-----------------|---|-------------|
| \overline{OE} | A | |
| L | H | H |
| L | L | L |
| H | X | Z |

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, NS, PW, and RGY packages.

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3.3-V ABT OCTAL BUFFER/DRIVER WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

| | |
|--|----------------------------|
| Supply voltage range, V_{CC} | –0.5 V to 4.6 V |
| Input voltage range, V_I (see Note 1) | –0.5 V to 7 V |
| Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1) | –0.5 V to 7 V |
| Voltage range applied to any output in the high state, V_O (see Note 1) | –0.5 V to $V_{CC} + 0.5$ V |
| Current into any output in the low state, I_O | 128 mA |
| Current into any output in the high state, I_O (see Note 2) | 64 mA |
| Input clamp current, I_{IK} ($V_I < 0$) | –50 mA |
| Output clamp current, I_{OK} ($V_O < 0$) | –50 mA |
| Package thermal impedance, θ_{JA} (see Note 3): DB package | 70°C/W |
| (see Note 3): DW package | 58°C/W |
| (see Note 3): GQN/ZQN package | 78°C/W |
| (see Note 3): NS package | 60°C/W |
| (see Note 3): PW package | 83°C/W |
| (see Note 4): RGY package | 37°C/W |
| Storage temperature range, T_{stg} | –65°C to 150°C |

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 3. The package thermal impedance is calculated in accordance with JESD 51-7.
 4. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 5)

| | | MIN | MAX | UNIT |
|--------------------------|------------------------------------|-----------------|-----|---------|
| V_{CC} | Supply voltage | 2.7 | 3.6 | V |
| V_{IH} | High-level input voltage | 2 | | V |
| V_{IL} | Low-level input voltage | | 0.8 | V |
| V_I | Input voltage | | 5.5 | V |
| I_{OH} | High-level output current | | –32 | mA |
| I_{OL} | Low-level output current | | 64 | mA |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | Outputs enabled | | 10 ns/V |
| $\Delta t/\Delta V_{CC}$ | Power-up ramp rate | 200 | | μs/V |
| T_A | Operating free-air temperature | –40 | 85 | °C |

NOTE 5: All unused inputs of the device must at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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3.3-V ABT OCTAL BUFFER/DRIVER

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP† | MAX | UNIT |
|--------------------------|--|---|--------------|------|-----------|---------------|
| V_{IK} | | $V_{CC} = 2.7\text{ V}$, $I_I = -18\text{ mA}$ | | | -1.2 | V |
| V_{OH} | | $V_{CC} = 2.7\text{ V to } 3.6\text{ V}$, $I_{OH} = -100\text{ }\mu\text{A}$ | $V_{CC}-0.2$ | | | V |
| | | $V_{CC} = 2.7\text{ V}$, $I_{OH} = -8\text{ mA}$ | 2.4 | | | |
| | | $V_{CC} = 3\text{ V}$, $I_{OH} = -32\text{ mA}$ | 2 | | | |
| V_{OL} | $V_{CC} = 2.7\text{ V}$ | $I_{OL} = 100\text{ }\mu\text{A}$ | | | 0.2 | V |
| | | $I_{OL} = 24\text{ mA}$ | | | 0.5 | |
| | $V_{CC} = 3\text{ V}$ | $I_{OL} = 16\text{ mA}$ | | | 0.4 | |
| | | $I_{OL} = 32\text{ mA}$ | | | 0.5 | |
| | | $I_{OL} = 64\text{ mA}$ | | | 0.55 | |
| I_I | Control inputs | $V_{CC} = 0\text{ or } 3.6\text{ V}$, $V_I = 5.5\text{ V}$ | | | 10 | μA |
| | | $V_{CC} = 3.6\text{ V}$, $V_I = V_{CC}\text{ or GND}$ | | | ± 1 | |
| | Data inputs | $V_{CC} = 3.6\text{ V}$, $V_I = V_{CC}$ | | | 1 | |
| | | $V_{CC} = 3.6\text{ V}$, $V_I = 0$ | | | -5 | |
| I_{off} | | $V_{CC} = 0$, $V_I\text{ or } V_O = 0\text{ to } 4.5\text{ V}$ | | | ± 100 | μA |
| I_{OZH} | | $V_{CC} = 3.6\text{ V}$, $V_O = 3\text{ V}$ | | | 5 | μA |
| I_{OZL} | | $V_{CC} = 3.6\text{ V}$, $V_O = 0.5\text{ V}$ | | | -5 | μA |
| I_{OZPU} | | $V_{CC} = 0\text{ to } 1.5\text{ V}$, $V_O = 0.5\text{ V to } 3\text{ V}$, $\overline{OE} = \text{don't care}$ | | | ± 100 | μA |
| I_{OZPD} | | $V_{CC} = 1.5\text{ V to } 0$, $V_O = 0.5\text{ V to } 3\text{ V}$, $\overline{OE} = \text{don't care}$ | | | ± 100 | μA |
| I_{CC} | $V_{CC} = 3.6\text{ V}$, $I_O = 0$, $V_I = V_{CC}\text{ or GND}$ | Outputs high | | | 0.19 | mA |
| | | Outputs low | | | 5 | |
| | | Outputs disabled | | | 0.19 | |
| ΔI_{CC}^\ddagger | | $V_{CC} = 3\text{ V to } 3.6\text{ V}$, One input at $V_{CC} - 0.6\text{ V}$, Other inputs at $V_{CC}\text{ or GND}$ | | | 0.2 | mA |
| C_i | | $V_I = 3\text{ V or } 0$ | | 4 | | pF |
| C_o | | $V_O = 3\text{ V or } 0$ | | 7 | | pF |

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

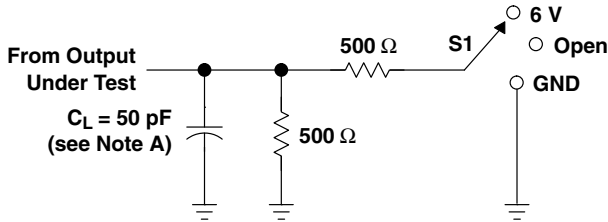
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} = 3.3 V ± 0.3 V | | | V _{CC} = 2.7 V | | UNIT |
|------------------|-----------------|----------------|------------------------------------|------|-----|-------------------------|-----|------|
| | | | MIN | TYP† | MAX | MIN | MAX | |
| t _{PLH} | A | Y | 1.1 | 2.3 | 3.5 | 3.8 | | ns |
| t _{PHL} | | | 1.3 | 2.1 | 3.3 | 3.6 | | |
| t _{PZH} | OE | Y | 1.1 | 2.5 | 4.5 | 5.3 | | ns |
| t _{PZL} | | | 1.4 | 2.7 | 4.4 | 4.9 | | |
| t _{PHZ} | OE | Y | 1.9 | 2.8 | 4.4 | 4.5 | | ns |
| t _{PLZ} | | | 1.8 | 2.9 | 4.4 | 4.4 | | |

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

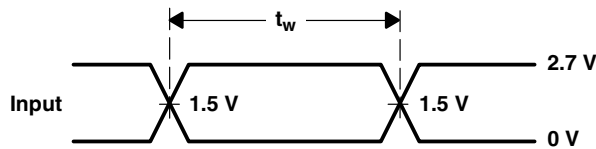


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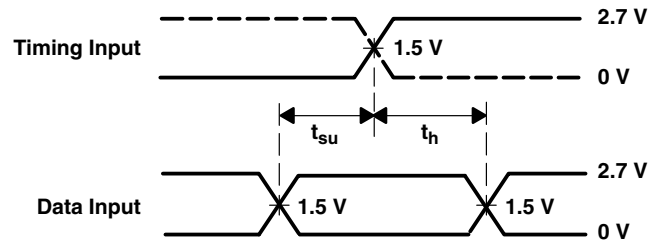
PARAMETER MEASUREMENT INFORMATION



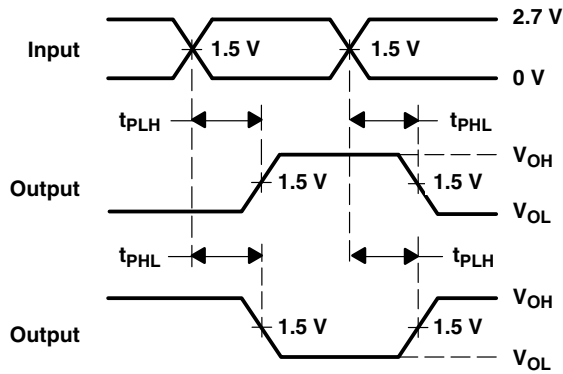
LOAD CIRCUIT



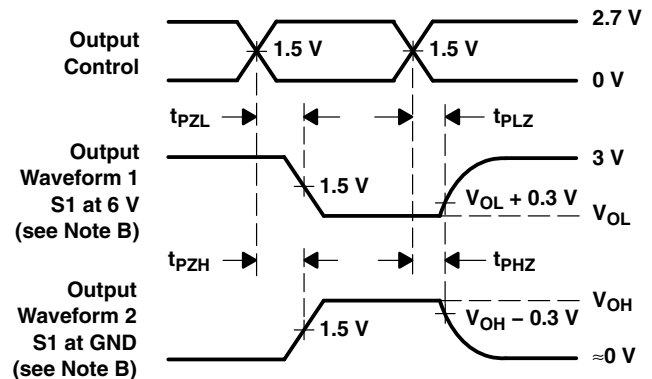
**VOLTAGE WAVEFORMS
PULSE DURATION**



**VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS**



**VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING**

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.
 E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/ Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|------------------|-----------------------|----------------------------|-----------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| SN74LVT244BDB | OBSOLETE | SSOP | DB | 20 | | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BDBLE | OBSOLETE | SSOP | DB | 20 | | TBD | Call TI | Call TI | |
| SN74LVT244BDBR | ACTIVE | SSOP | DB | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BDBRE4 | ACTIVE | SSOP | DB | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BDBRG4 | ACTIVE | SSOP | DB | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BDW | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BDWE4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BDWG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BDWR | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BDWRE4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BDWRG4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BGQNR | LIFEBUY | BGA MICROSTAR JUNIOR | GQN | 20 | 1000 | TBD | SNPB | Level-1-240C-UNLIM | |
| SN74LVT244BNSR | ACTIVE | SO | NS | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BNSRG4 | ACTIVE | SO | NS | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BPW | ACTIVE | TSSOP | PW | 20 | 70 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BPWE4 | ACTIVE | TSSOP | PW | 20 | 70 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BPWG4 | ACTIVE | TSSOP | PW | 20 | 70 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/ Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|-------------------|-----------------------|----------------------------|-----------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| SN74LVT244BPWLE | OBSOLETE | TSSOP | PW | 20 | | TBD | Call TI | Call TI | |
| SN74LVT244BPWR | ACTIVE | TSSOP | PW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BPWRE4 | ACTIVE | TSSOP | PW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BPWRG4 | ACTIVE | TSSOP | PW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| SN74LVT244BRGYR | ACTIVE | VQFN | RGY | 20 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| SN74LVT244BRGYRG4 | ACTIVE | VQFN | RGY | 20 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| SN74LVT244BZQNR | ACTIVE | BGA MICROSTAR JUNIOR | ZQN | 20 | 1000 | Green (RoHS & no Sb/Br) | SNAGCU | Level-1-260C-UNLIM | |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

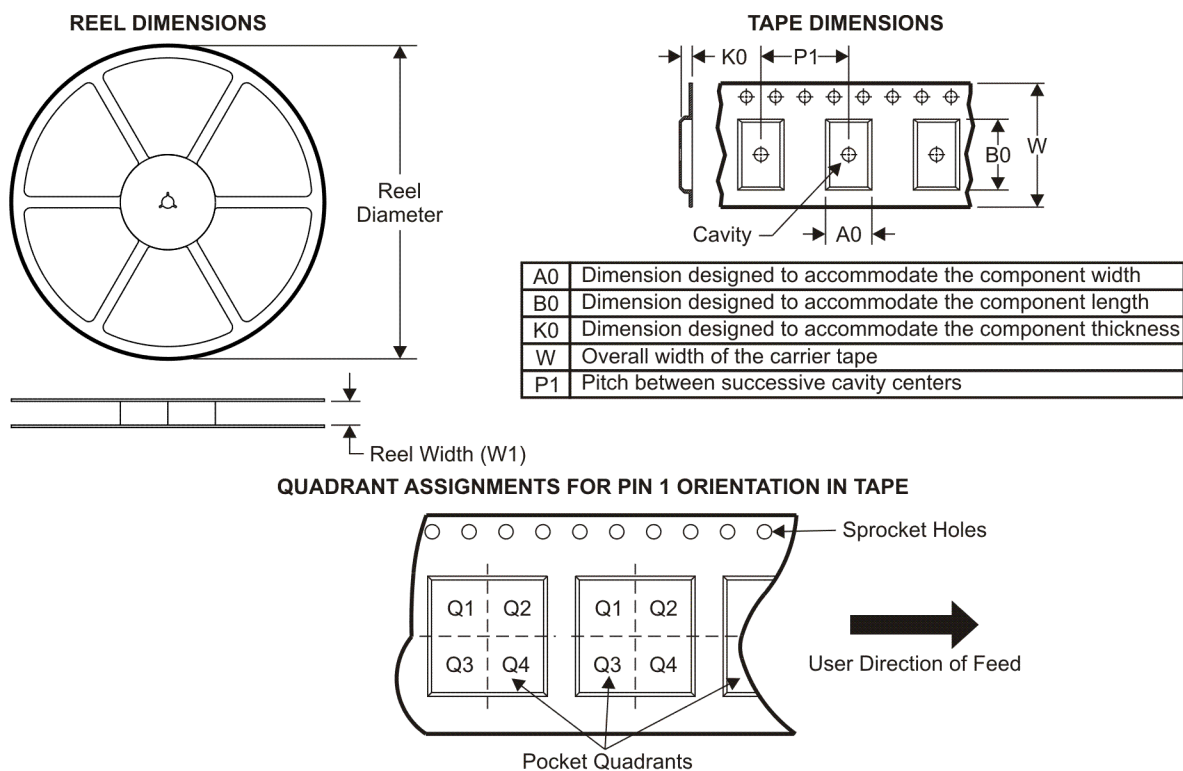
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|----------------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LVT244BDBR | SSOP | DB | 20 | 2000 | 330.0 | 16.4 | 8.2 | 7.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74LVT244BDWR | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.0 | 2.7 | 12.0 | 24.0 | Q1 |
| SN74LVT244BGQNR | BGA MICROSTAR JUNIOR | GQN | 20 | 1000 | 330.0 | 12.4 | 3.3 | 4.3 | 1.5 | 8.0 | 12.0 | Q1 |
| SN74LVT244BNSR | SO | NS | 20 | 2000 | 330.0 | 24.4 | 8.2 | 13.0 | 2.5 | 12.0 | 24.0 | Q1 |
| SN74LVT244BPWR | TSSOP | PW | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |
| SN74LVT244BRGYR | VQFN | RGY | 20 | 3000 | 330.0 | 12.4 | 3.8 | 4.8 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74LVT244BZQNR | BGA MICROSTAR JUNIOR | ZQN | 20 | 1000 | 330.0 | 12.4 | 3.3 | 4.3 | 1.5 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS

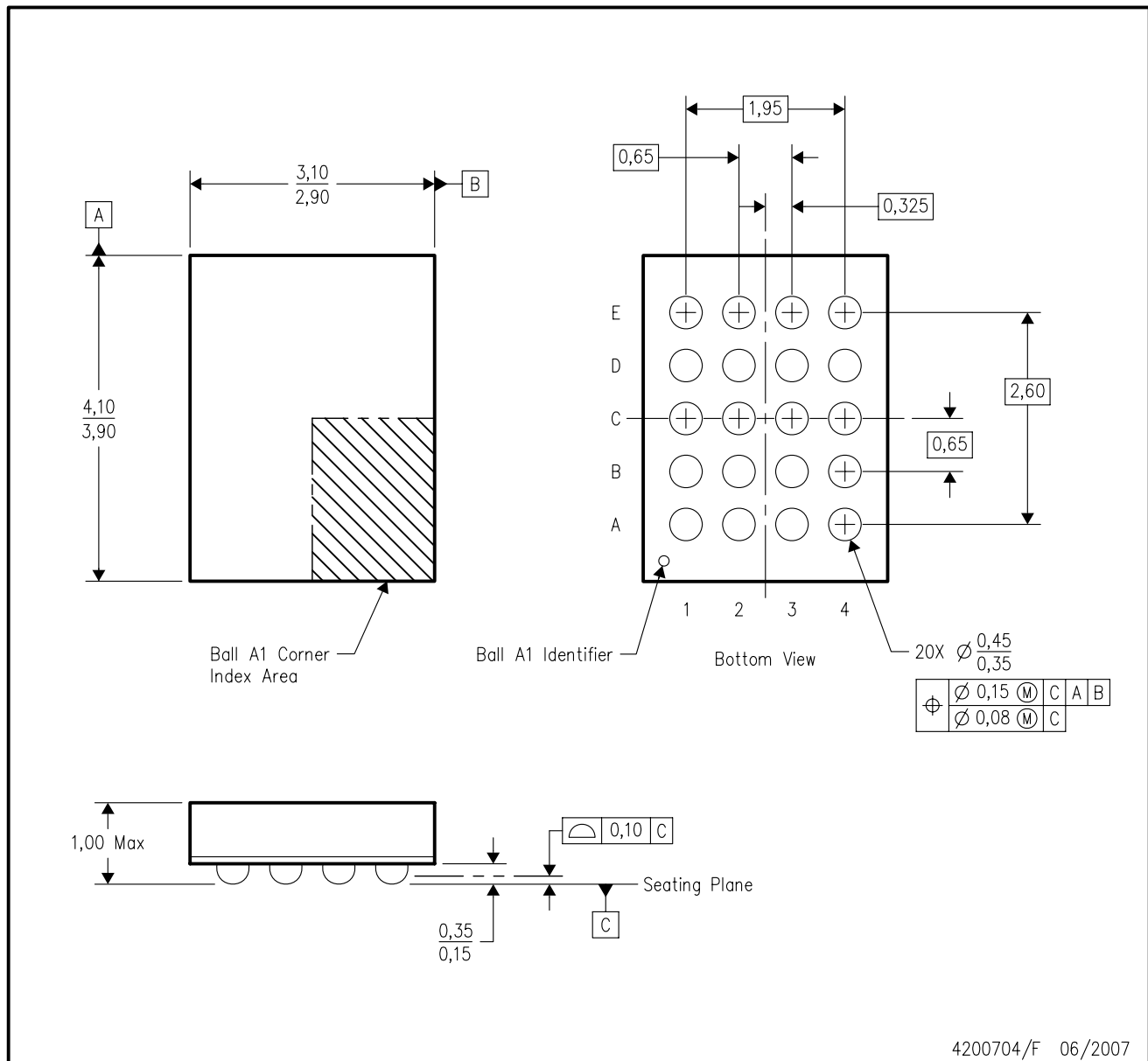


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------------|----------------------|-----------------|------|------|-------------|------------|-------------|
| SN74LVT244BDBR | SSOP | DB | 20 | 2000 | 346.0 | 346.0 | 33.0 |
| SN74LVT244BDWR | SOIC | DW | 20 | 2000 | 346.0 | 346.0 | 41.0 |
| SN74LVT244BGQNR | BGA MICROSTAR JUNIOR | GQN | 20 | 1000 | 340.5 | 338.1 | 20.6 |
| SN74LVT244BNSR | SO | NS | 20 | 2000 | 346.0 | 346.0 | 41.0 |
| SN74LVT244BPWR | TSSOP | PW | 20 | 2000 | 346.0 | 346.0 | 33.0 |
| SN74LVT244BRGYR | VQFN | RGY | 20 | 3000 | 346.0 | 346.0 | 29.0 |
| SN74LVT244BZQNR | BGA MICROSTAR JUNIOR | ZQN | 20 | 1000 | 340.5 | 338.1 | 20.6 |

GQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY

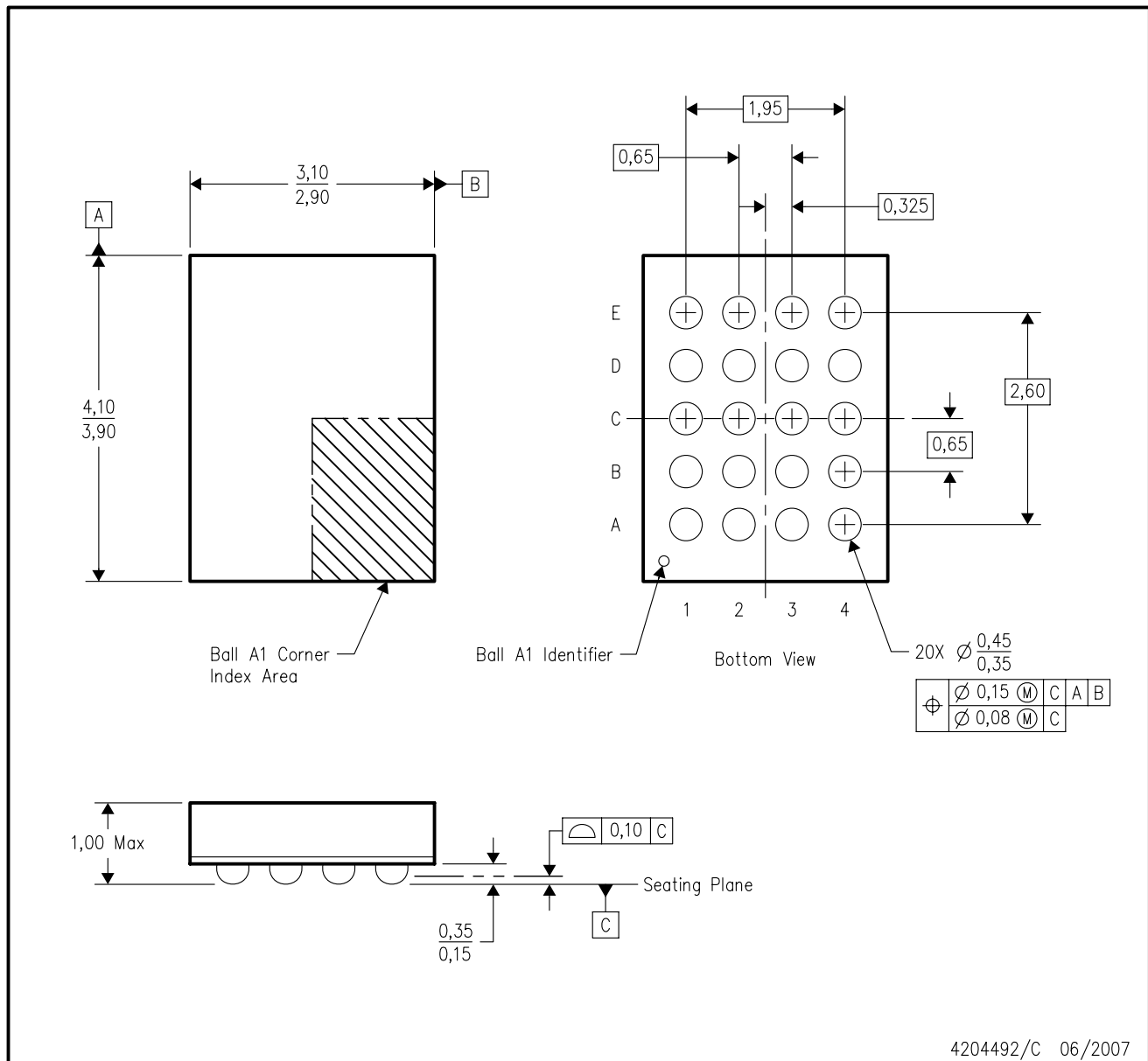


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- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-285 variation BC-2.
 - D. This package is tin-lead (SnPb). Refer to the 20 ZQN package (drawing 4204492) for lead-free.

ZQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY

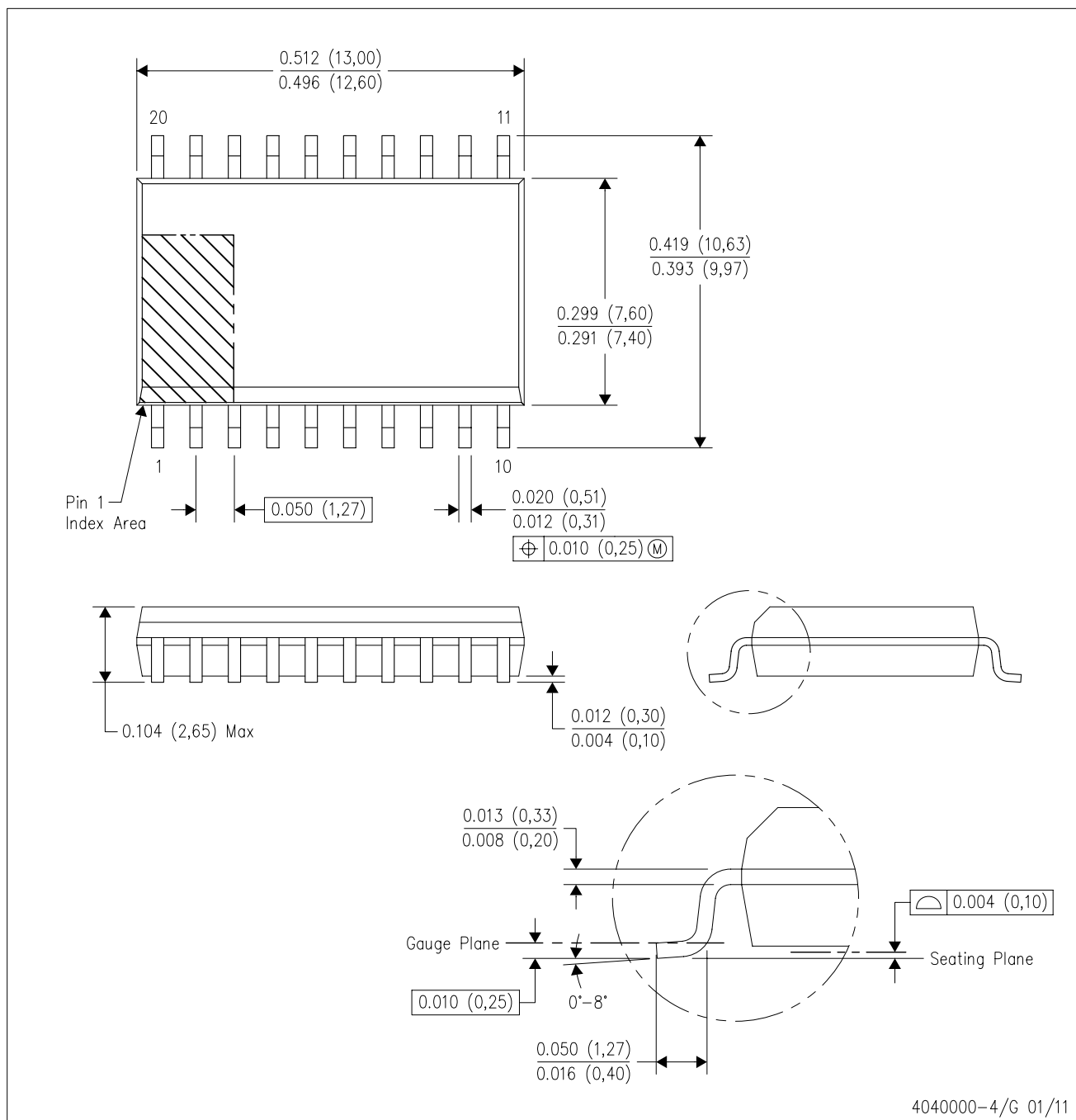


4204492/C 06/2007

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-285 variation BC-2.
 - D. This package is lead-free. Refer to the 20 GQN package (drawing 4200704) for tin-lead (SnPb).

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

PW (R-PDSO-G20)

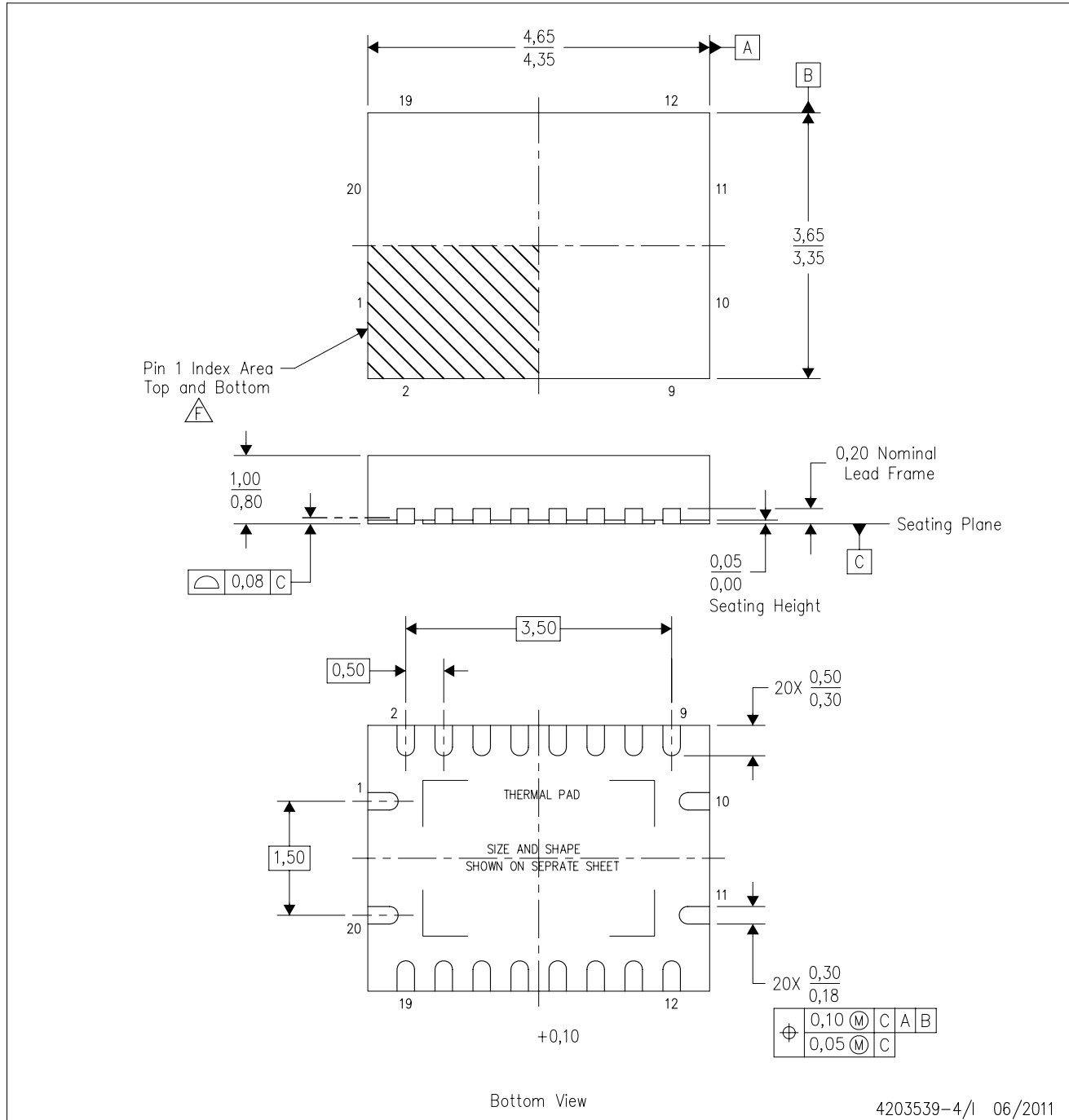
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

RGY (R-PVQFN-N20)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- F** Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
- Package complies to JEDEC MO-241 variation BA.

RGY (R-PVQFN-N20)

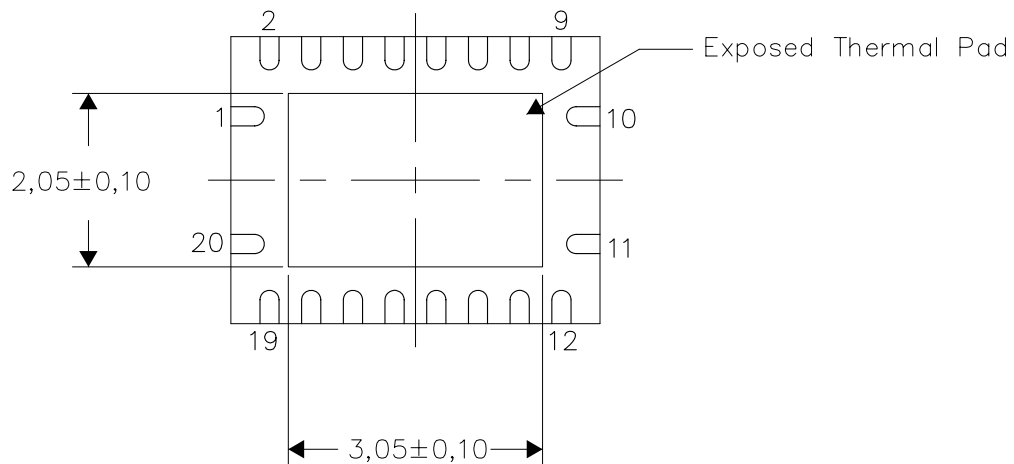
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

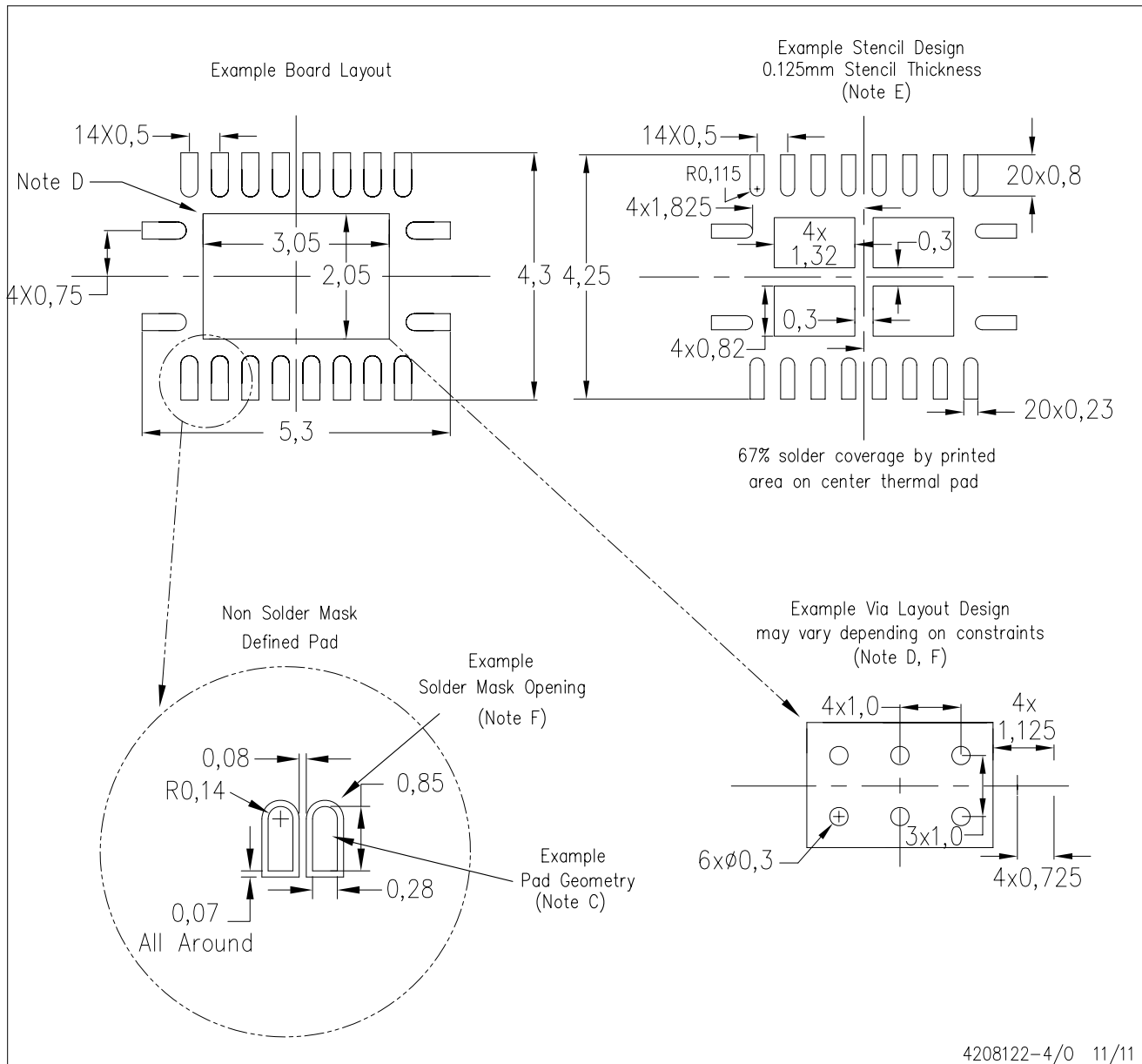
Exposed Thermal Pad Dimensions

4206353-4/0 11/11

NOTE: All linear dimensions are in millimeters

RGY (R-PVQFN-N20)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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